In the Claims:

1. (Currently Amended) A semiconductor device testing socket or adapter device adapted for carrying a semiconductor device to be tested, the ~~semiconductor device testing~~ socket or adapter device comprising:

a plurality of positioning pins for positioning the socket or adapter device on a circuit board; and

a plurality of resilient connection pins, wherein the plurality of resilient connection pins ~~extend~~ extends from a lower surface of a housing of the socket or adapter device in a downward direction, the plurality of resilient connection pins [[being]] comprising:

~~configured to be connected~~ connections to [[a]] corresponding ~~contact device~~ contacts on the circuit board for [[by]] solderless surface mounting, wherein the connections are configured by compressing the plurality of resilient connection pins to shorten a pin extension length of the plurality of resilient connection pins, [[and]]

end sections, wherein the end sections ~~of the connection pins having a shape bent back in an upward~~ are wave shaped along a vertical direction, and ~~with respective tips of the~~

tips of the end sections, wherein the tips of the end sections are [[being]] arranged outside the housing, and wherein the wave shaped ~~bent back~~ end sections of the plurality of resilient connection pins, viewed from a bottom of the socket or adapter device, are [[being]] arranged obliquely with an angle of about 45° ~~between 30° and 60°~~ with respect to a longitudinal axis of the socket or adapter device so as to avoid contact between a shape end section of a first connection pin and a shape end section of an adjacent second connection pin when the ~~semiconductor device testing~~ socket or adapter device is mounted to the contacts on the circuit

board. ~~contact device, wherein each connection pin comprises a maximum extension length of between about 0.1mm and about 1.5mm.~~

2. (Previously Presented) The socket or adapter device according to claim 1, wherein the socket or adapter device is a semiconductor device testing socket or a semiconductor device testing adapter, respectively, which is configured for testing a semiconductor device such that the socket or adapter device can be loaded with a corresponding semiconductor device.

3. (Currently Amended) The socket or adapter device according to claim 2, wherein the socket or adapter device is a burn-in testing socket or a burn-in testing adapter, respectively, which is configured for performing a burn-in test and can be loaded with [[a]] the corresponding semiconductor device.

4. (Currently Amended) The socket or adapter device according to claim 1, wherein [[the]] a surface of the plurality of resilient connection pins is coated with gold. ~~are made of a flexible or resilient material.~~

5. (Currently Amended) The socket or adapter device according to claim 4, wherein the ~~material includes~~ the plurality of resilient connection pins are made of copper and/or beryllium.

6. (Canceled)

7. (Currently Amended) The socket or adapter device according to claim 1, wherein a device comprising the ~~contact device is a~~ contacts on the circuit board are configured to be connected to a testing apparatus.

8. (Currently Amended) The socket or adapter device according to claim 1, wherein a device comprising the ~~contact device~~ contacts is a testing apparatus.

9. (Currently Amended) A system, comprising:

at least one socket or adapter device; and

at least one semiconductor device testing apparatus, wherein the socket or adapter device comprises a plurality of resilient connection pins, the resilient connection pins ~~which are~~ configured to be connected to a corresponding contact device for connection to the testing apparatus; [[and]]

wherein the resilient connection pins extend from a lower surface of a housing of the socket or adapter device in a downward direction, end sections of the resilient connection pins having a wave shape comprising a shape bent back in an upward direction followed by a shape bent down in the downward direction with respective tips of the end sections being arranged outside the housing, the wave shaped ~~bent back~~ end sections of the resilient connection pins viewed from a bottom of the socket or adapter device being arranged obliquely with an angle of about 45° ~~between 30° and 60°~~ with respect to a longitudinal axis of the socket or adapter device so as to avoid contact between a bent back end section of a first connection pin and a bent back end section of an adjacent second connection pin when the socket or adapter device is mounted to the contact device, and the resilient connection pins are connected to the contact device by surface mounting~~, wherein each connection pin comprises a maximum extension length of between about 0.1mm and about 1.5mm~~.

10. (Currently Amended) The system according to claim 9, wherein the resilient connection pins are connected to the contact device without soldering.

11. (Currently Amended) The system according to claim 9, wherein a device is provided such that the resilient connection pins are pressed against the contact device.

12. (Original) The system according to claim 11, wherein the device is an appropriate screw connection.

13. (Original) The system according to claim 11, wherein the device is an appropriate clamping connection.

14. (Currently Amended) The system according to claim 10, wherein the ~~socket or adapter device comprises a plurality of~~ resilient connection ~~pins, each being~~ pins are connected to corresponding contact devices, [[and]] wherein the resilient connection pins [[each]] are connected to the respectively corresponding contact devices without soldering.

15. (Currently Amended) A method for testing semiconductor devices, the method comprising:

connecting a socket or adapter device to a testing system, wherein a plurality of resilient connection pins are connected to a corresponding contact device; and

loading the socket or adapter device with a semiconductor device to be tested, wherein the connection pins extend from a lower surface of a housing of the socket or adapter device in a downward direction, end sections of the connection pins having a bent shape comprising a bend [[bent]] back in an upward direction followed by a bend in a downward direction with respective tips of the end sections being arranged outside the housing, the end sections of the connection pins viewed from a bottom of the socket or adapter device being arranged obliquely with an angle of about 45° ~~between 30° and 60°~~ with respect to a longitudinal axis of the socket or

adapter device so as to avoid contact between a bent [[back]] end section of a first resilient connection pin and a bent [[back]] end section of an adjacent second resilient connection pin when the socket or adapter device is mounted to the contact device, and the connection of the connection pins to the contact device is by solderless surface mounting, wherein each connection pin comprises a maximum extension length of between about 0.1mm and about 1.5mm.

16. (New) The socket or adapter device according to claim 1, wherein each connection pin of the plurality of resilient connection pins comprises a maximum extension length of between about 0.1mm and about 1.5mm.